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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	225400
Number of Logic Elements/Cells	597000
Total RAM Bits	53248000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-FCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxmb6r3f43c4n

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Electrical Characteristics Page 7

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	neceiver arialog power supply (right side)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL}	Transmitter analog newer cupply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (left side)	dx, d3, d1	0.97	1.0	1.03	V
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right side)	এম, ৫১, ৫।	0.97	1.0	1.03	V
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V _{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Notes to Table 7:

⁽¹⁾ This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

⁽²⁾ Refer to Table 8 to select the correct power supply level for your design.

⁽³⁾ When using ATX PLLs, the supply must be 3.0 V.

⁽⁴⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Page 8 Electrical Characteristics

Table 8 shows the transceiver power supply voltage requirements for various conditions.

Table 8. Transceiver Power Supply Voltage Requirements

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB (2)	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true:					
■ Data rate > 10.3 Gbps.	All	1.05			
■ DFE is used.					
If ANY of the following conditions are true ⁽¹⁾ :			3.0		
ATX PLL is used.					
■ Data rate > 6.5Gbps.	All	1.0			
■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.				1.5	V
If ALL of the following	C1, C2, I2, and I3YY	0.90	2.5		
conditions are true: ATX PLL is not used.					
■ Data rate ≤ 6.5Gbps.	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		
DFE, AEQ, and EyeQ are not used.					

Notes to Table 8:

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Page 10 Electrical Characteristics

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48 - Ω , 60 - Ω , 80 - Ω , and 240 - Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCIO} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- Ω and 120- Ω R _T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Re	sistance	Tolerance		
Symbol	Description	Conditions C1		C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%

⁽¹⁾ OCT calibration accuracy is valid at the time of calibration only.

Electrical Characteristics Page 17



You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Switching Characteristics Page 25

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL (2))		fPLL	
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 ⁽³⁾	14.1	_	6	12.5	_	6	3.125	_	3
x6 ⁽³⁾	_	14.1	6	_	12.5	6	_	3.125	6
x6 PLL Feedback ⁽⁴⁾	_	14.1	Side- wide	_	12.5	Side- wide	_	_	_
xN (PCIe)	_	8.0	8	_	5.0	8	_	_	_
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above	3.125	3.125	Up to 13 channels above
XIV (IVALIVE PRY IP)	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.99	7.99	and below PLL	J. 125	3.123	and below PLL

Notes to Table 24:

⁽¹⁾ Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

⁽²⁾ ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

⁽³⁾ Channel span is within a transceiver bank.

⁽⁴⁾ Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Page 26 Switching Characteristics

Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode ⁽²⁾	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO	3	C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
		I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
		C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
		C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

⁽³⁾ The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Page 30 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive Speed Grade		S	Unit				
Description		Min	Тур	Max	Min	Тур	Max	5		
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>		
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1L, 1.4-V PC	ML, 1.5-V P(CML, 2.5-V I and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS		
otandardo	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS								
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz		
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz		
Rise time	20% to 80%	_	- 400		_	_	400			
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps		
Duty cycle	_	45	_	55	45	_	55	%		
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz		
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%		
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω		
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V		
	RX reference clock pin	_	_	1.2	_	_	1.2			
Absolute V _{MIN}	_	-0.4	_	_	-0.4		_	V		
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV		
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV		
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	V				
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV		

Switching Characteristics Page 31

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2		_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration (16), (20)	$V_{CCR_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
Johnguration 7, 17	GX channels				(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

Page 34 Switching Characteristics

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)

Symbol/ Description	Conditions		Transceiver Speed Grade 2			Transceiver Speed Grade 3		Unit
Description		Min	Тур	Max	Min Typ Max			
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{LTB} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) tLTD is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Page 38 Switching Characteristics

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance							
Symbol	C1, C2, C2L, I2, and I2L	12, and C3, I3, I3L, and I3YY C4, I4		Unit				
Global and Regional Clock	717	650	580	MHz				
Periphery Clock	550	500	500	MHz				

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Page 42 Switching Characteristics

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

		Peformance								
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit		
		Modes us	ing Three	DSPs	•					
One complex 18 x 25	425	425	415	340	340	275	265	MHz		
Modes using Four DSPs										
One complex 27 x 27	465	465	465	380	380	300	290	MHz		

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 1 of 2)

		Resour	ces Used	d Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, I2L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x16 depth (3)	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Switching Characteristics Page 45

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3, I3, I3L, I3YY			C4,I4			Unit
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

Page 48 Switching Characteristics

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled

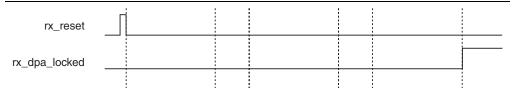


Table 37 lists the DPA lock time specifications for Stratix V devices.

Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only (1), (2), (3)

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽⁴⁾	Maximum
SPI-4	0000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
Farallel hapiu 1/0	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
IVIISCEIIAIIEOUS	01010101	8	32	640 data transitions

Notes to Table 37:

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the **LVDS** soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps. Table 38 lists the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate \geq 1.25 Gbps.

Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate \geq 1.25 Gbps

LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification

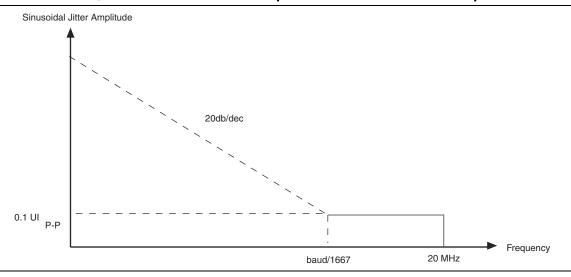
Switching Characteristics Page 49

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate \geq 1.25 Gbps

Jitter Fr	Jitter Frequency (Hz)					
F1	10,000	25.000				
F2	17,565	25.000				
F3	1,493,000	0.350				
F4	50,000,000	0.350				

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices (1)

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

Note to Table 39:

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Page 50 Switching Characteristics

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 2 of 2)

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Notes to Table 40:

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices (1)

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 1 of 2) (2), (3)

Clock Network	Parameter	Symbol	C	1	C2, C2L	, I2, I2L	C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t _{JIT(per)}	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	t _{JIT(cc)}	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t _{JIT(per)}	-75	75	- 75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	t _{JIT(cc)}	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	t _{JIT(duty)}	- 75	75	- 75	75	-90	90	-90	90	ps

⁽¹⁾ This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a −2 speed grade is ±78 ps or ±39 ps.

Page 54 Configuration Specification

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)
Stratix V E (1)	5SEE9	_	342,742,976	700,888
Stratix V L 17	5SEEB	_	342,742,976	700,888

Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Banker		Active Serial (1))	Fast Passive Parallel ⁽²⁾			
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)	
	A3	4	100	0.534	32	100	0.067	
	AS	4	100	0.344	32	100	0.043	
	A4	4	100	0.534	32	100	0.067	
	A5	4	100	0.675	32	100	0.084	
	A7	4	100	0.675	32	100	0.084	
GX	A9	4	100	0.857	32	100	0.107	
	AB	4	100	0.857	32	100	0.107	
	B5	4	100	0.676	32	100	0.085	
	B6	4	100	0.676	32	100	0.085	
	В9	4	100	0.857	32	100	0.107	
	BB	4	100	0.857	32	100	0.107	
GT	C5	4	100	0.675	32	100	0.084	
G1	C7	4	100	0.675	32	100	0.084	

Page 56 Configuration Specification

Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FPP ×32	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

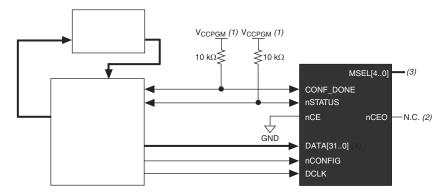
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

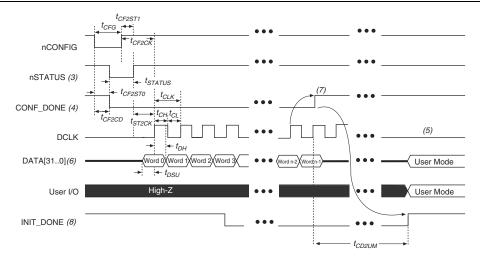
- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM}.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP $\times 8$, use DATA [7..0]. If you use FPP $\times 16$, use DATA [15..0].

Configuration Specification Page 57

FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 (1), (2)



Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA[] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the <code>INIT_DONE</code> pin is configured into the device, the <code>INIT_DONE</code> goes low.

Page 68 Glossary

Table 60. Glossary (Part 4 of 4)

Letter	Subject	Definitions
	V _{CM(DC)}	DC common mode input voltage.
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	V _{IH(AC)}	High-level AC input voltage
	V _{IH(DC)}	High-level DC input voltage
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	V _{IL(AC)}	Low-level AC input voltage
	V _{IL(DC)}	Low-level DC input voltage
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	V _{SWING}	Differential input voltage
	V _X	Input differential cross point voltage
	V _{OX}	Output differential cross point voltage
W	W	High-speed I/O block—clock boost factor
Χ		
Υ		_
Z		

Page 70 Document Revision History

Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes
		■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.
		■ Added the I3YY speed grade to the V _{CC} description in Table 6.
		■ Added the I3YY speed grade to V _{CCHIP_L} , V _{CCHIP_R} , V _{CCHSSI_L} , and V _{CCHSSI_R} descriptions in Table 7.
		■ Added 240-Ω to Table 11.
		■ Changed CDR PPM tolerance in Table 23.
		■ Added additional max data rate for fPLL in Table 23.
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.
		■ Changed CDR PPM tolerance in Table 28.
		■ Added additional max data rate for fPLL in Table 28.
	3.3	■ Changed the mode descriptions for MLAB and M20K in Table 33.
November 2014		■ Changed the Max value of f _{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36.
		■ Changed the frequency ranges for C1 and C2 in Table 39.
		■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.
		■ Added note about nSTATUS to Table 50, Table 51, Table 54.
		■ Changed the available settings in Table 58.
		■ Changed the note in "Periphery Performance".
		■ Updated the "I/O Standard Specifications" section.
		■ Updated the "Raw Binary File Size" section.
		■ Updated the receiver voltage input range in Table 22.
		■ Updated the max frequency for the LVDS clock network in Table 36.
		■ Updated the DCLK note to Figure 11.
		■ Updated Table 23 VO _{CM} (DC Coupled) condition.
		■ Updated Table 6 and Table 7.
		■ Added the DCLK specification to Table 55.
		■ Updated the notes for Table 47.
		■ Updated the list of parameters for Table 56.
November 2013	3.2	■ Updated Table 28
November 2013	3.1	■ Updated Table 33
November 2013	3.0	■ Updated Table 23 and Table 28
October 2013	2.9	■ Updated the "Transceiver Characterization" section
	2.8	■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59
October 2013		■ Added Figure 1 and Figure 3
		■ Added the "Transceiver Characterization" section
		■ Removed all "Preliminary" designations.